

1.10mm Height 1206 Package
Infrared Chip LED
Technical Data Sheet

Part No.: LL-S150IRC-2A



Features:

- ◇ Package in 8mm tape on 7" diameter reel.
- ◇ Compatible with automatic placement equipment.
- ◇ Compatible with infrared and vapor phase reflow solder process.
- ◇ Mono-color type.
- ◇ The product itself will remain within RoHS compliant Version.

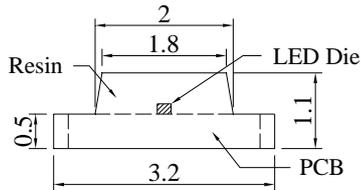
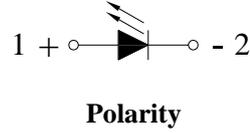
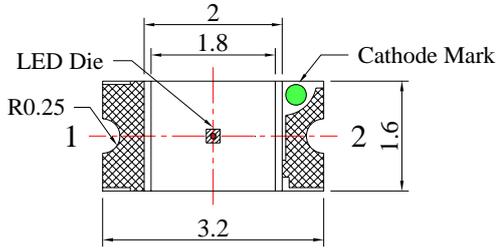
Descriptions:

- ◇ The S150IR is an infrared emitting diode in miniature SMD package which is molded in a water clear plastic with flat top view lens.
- ◇ The device is spectrally matched with photodiode and phototransistor.

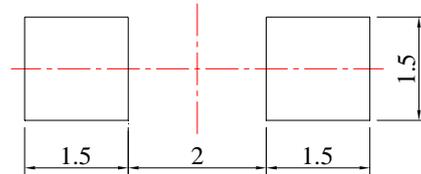
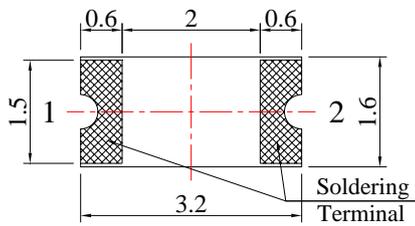
Applications:

- ◇ PCB mounted infrared sensor.
- ◇ Infrared emitting for miniature light barrier.
- ◇ Floppy disk drive.
- ◇ Optoelectronic switch.
- ◇ Smoke detector.

Package Dimension:



Recommended Soldering Pad Dimensions



Unit: mm
Tolerance: $\pm 0.10\text{mm}$

1. Soldering terminal may shift in x, y direction.
2. Polarity referring onto the cathode mark is reversed on the UR/HR/SR.

Part No.	Chip Material	Lens Color	Source Color
LL-S150IRC-2A	GaAlAs	Water Clear	Infrared

Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.10\text{mm}$ (.004") unless otherwise specified.
3. Specifications are subject to change without notice.

Absolute Maximum Ratings at Ta=25°C

Parameters	Symbol	Max.	Unit
Power Dissipation	PD	100	mW
Peak Forward Current (1/10 Duty Cycle, 0.1ms Pulse Width)	IFP	1.00	A
Forward Current	IF	50	mA
Reverse Voltage	VR	5	V
Operating Temperature Range	Topr	-25°C to +80°C	
Storage Temperature Range	Tstg	-40°C to +85°C	
Lead Soldering Temperature	Tsld	260°C for 5 Seconds	

Electrical Optical Characteristics at Ta=25°C

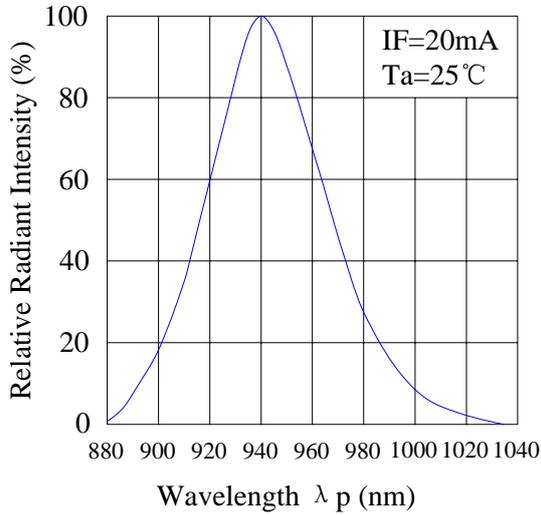
Parameters	Symbol	Min.	Typ.	Max.	Unit	Test Condition
Radiant Intensity *	Ee	0.20	0.35	---	mW/sr	IF=20mA
		---	2.50	---		IF=100mA (Pulse Width≤100μs, Duty≤1%)
Viewing Angle *	2θ 1/2	---	140	---	Deg	IF=20mA (Note 2)
Peak Emission Wavelength	λp	---	940	---	nm	IF=20mA (Note 3)
Spectral Bandwidth	Δλ	---	50	---	nm	IF=20mA
Forward Voltage	VF	0.80	1.20	1.50	V	IF=20mA
		---	1.60	1.80		IF=100mA (Pulse Width≤100μs, Duty≤1%)
Reverse Current	IR	---	---	10	μA	VR=5V

Notes:

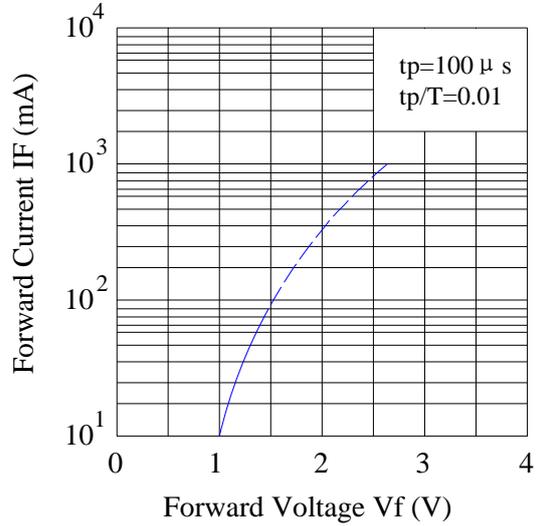
- Luminous (Radiant) Intensity Measurement allowance is ± 10%.
- θ_{1/2} is the off-axis angle at which the luminous intensity is half the axial luminous intensity.
- The dominant wavelength (λ_p) is derived from the CIE chromaticity diagram and represents the single wavelength which defines the color of the device.

Typical Electrical / Optical Characteristics Curves
 (25°C Ambient Temperature Unless Otherwise Noted)

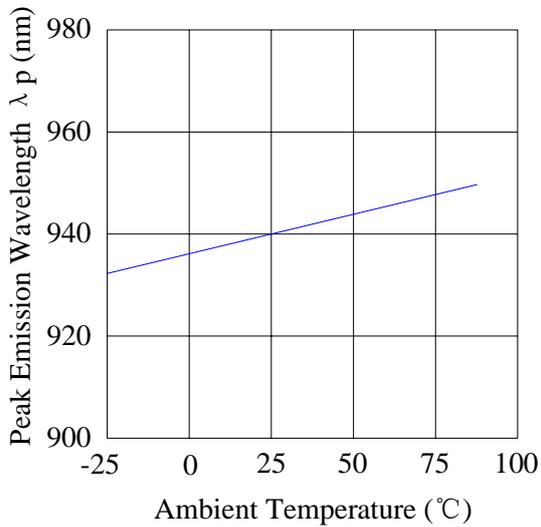
Spectral Distribution



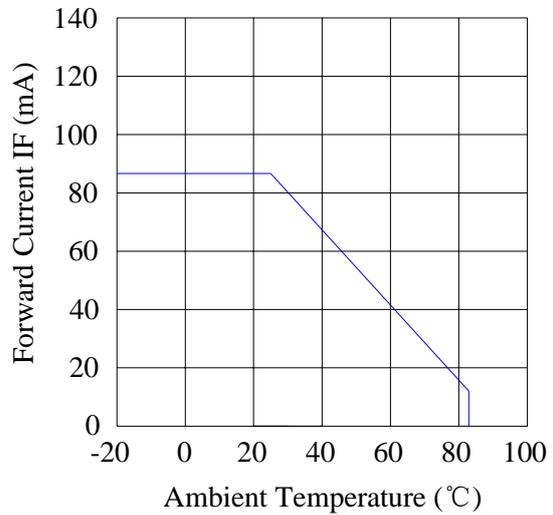
Forward Current & Forward Voltage



Peak Emission Wavelength & Ambient Temperature

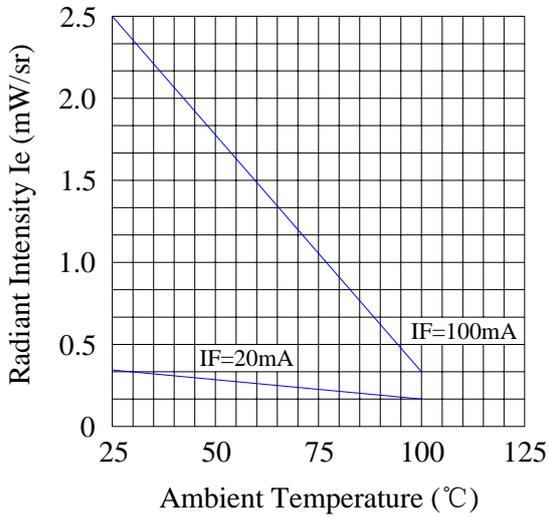


Forward Current & Ambient Temperature

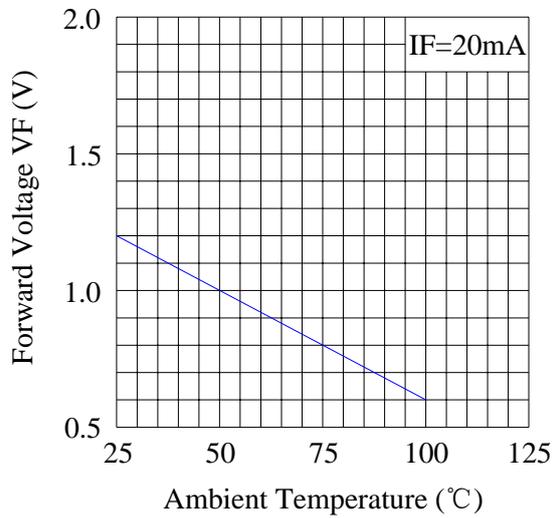




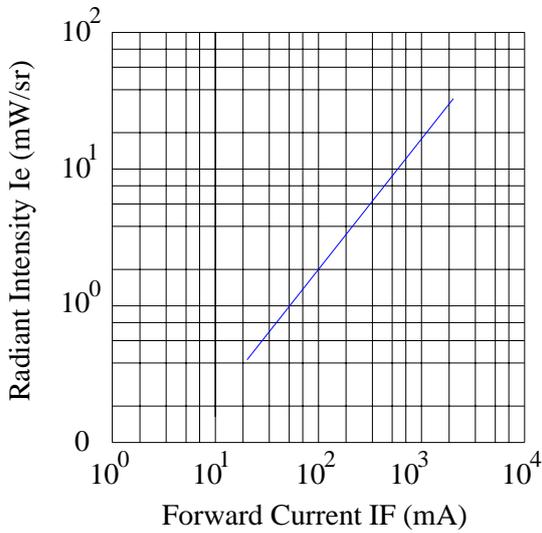
Relative Intensity & Ambient Temperature



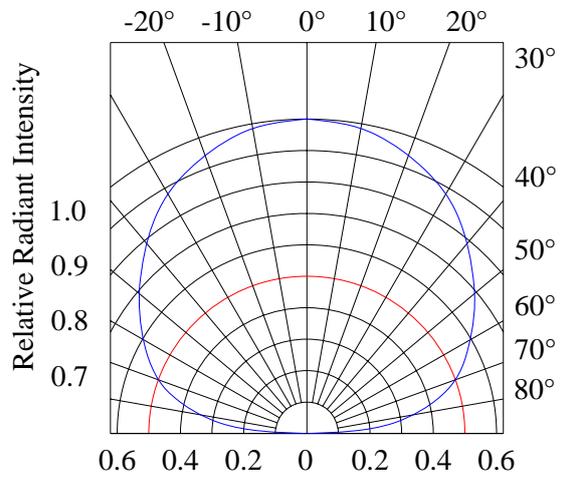
Forward Voltage & Ambient Temperature



Relative Intensity & Forward Current



Relative Radiant Intensity & Angular Displacement



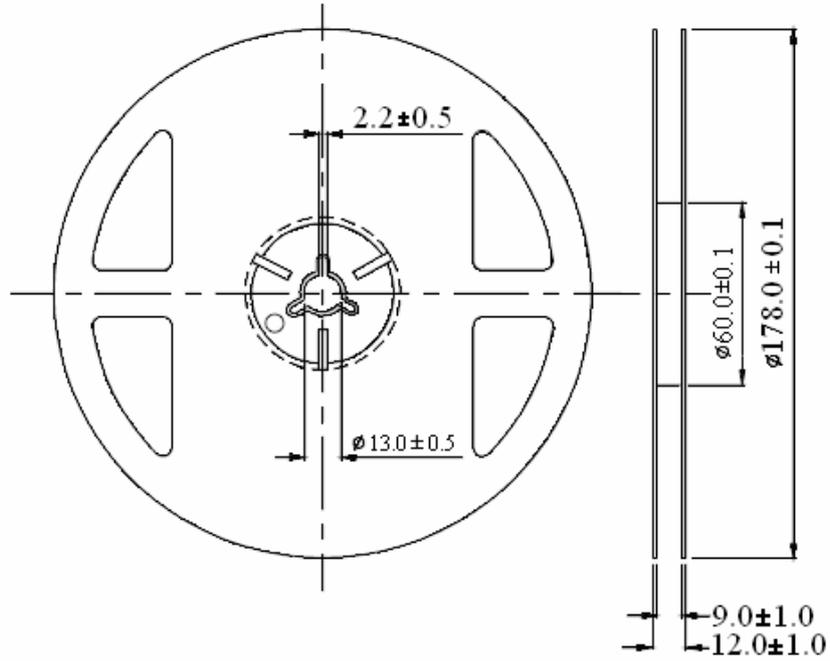
Reliability Test Items And Conditions:

The reliability of products shall be satisfied with items listed below:

Confidence level: 90%.

LTPD: 10%.

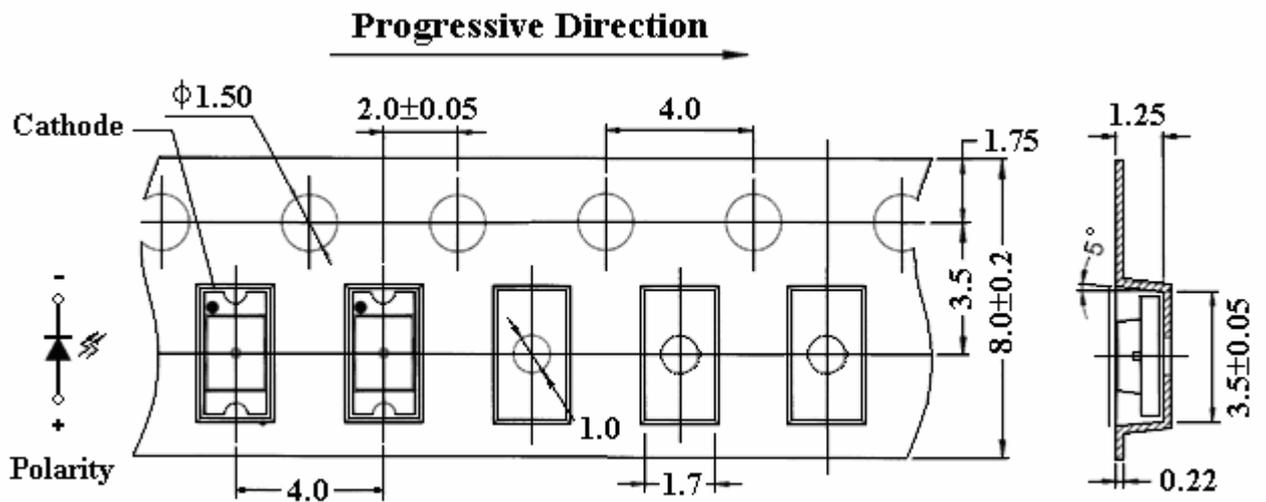
No.	Item	Test Conditions	Test Hours/ Cycles	Sample Sizes	Failure Judgment Criteria	Ac/ Re
1	Reflow Soldering	TEMP.: 260°C±5°C 5secs	6mins	22pcs	$IR \geq U * 2$ $Ee \leq L * 0.8$ $VF \geq U * 1.2$ U: Upper Specification Limit L: Lower Specification Limit	0/1
2	Temperature Cycle	H: +100°C 15mins ┆ 5 mins ┆ L: -40°C 15mins	50Cycles	22pcs		0/1
3	Thermal Shock	H: +100°C 15mins ┆ 10mins ┆ L: -10°C 5mins	50Cycles	22pcs		0/1
4	High Temperature Storage	TEMP.: +100°C	1000hrs	22pcs		0/1
5	Lower Temperature Storage	TEMP.: -40°C	1000hrs	22pcs		0/1
6	DC Operating Life	$V_{CE}=5V$	1000hrs	22pcs		0/1
7	High Temperature/ High Humidity	85°C / 85% R.H	1000hrs	22pcs		0/1

Reel Dimensions:


Unit: mm
Tolerance: ± 0.25 mm

Carrier Tape Dimensions:

Loaded quantity 3000 PCS Per reel.



Unit: mm
Tolerance: ± 0.10 mm

Please read the following notes before using the product:

1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

2.1 Do not open moisture proof bag before the products are ready to use.

2.2 Before opening the package, the LEDs should be kept at 30°C or less and 90%RH or less.

2.3 The LEDs should be used within a year.

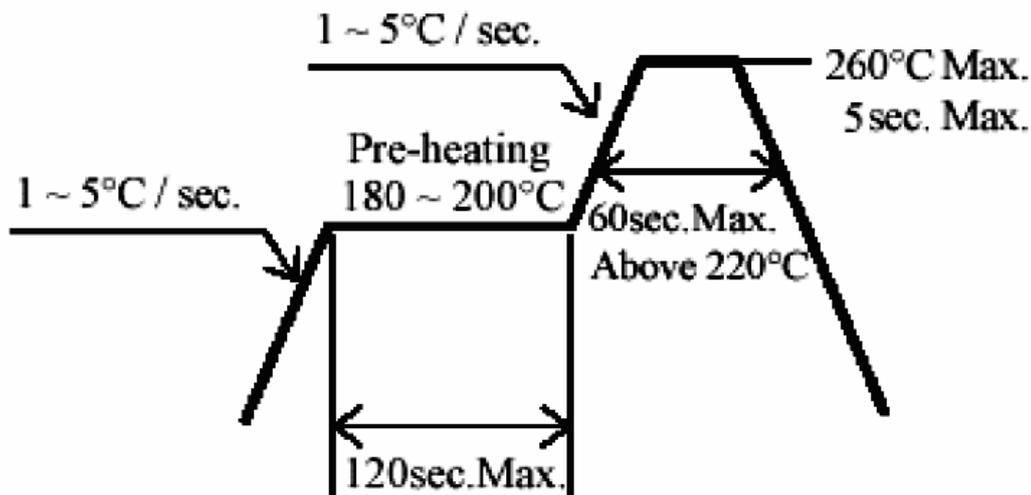
2.4 After opening the package, the LEDs should be kept at 30°C or less and 70%RH or less.

2.5 The LEDs should be used within 168 hours (7 days) after opening the package.

2.6 If the moisture adsorbent material (silica gel) has fabled away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions. Baking treatment: 60±5°C for 24 hours.

3. Soldering Condition

3.1 Pb-free solder temperature profile.



3.2 Reflow soldering should not be done more than two times.

3.3 When soldering, do not put stress on the LEDs during heating.

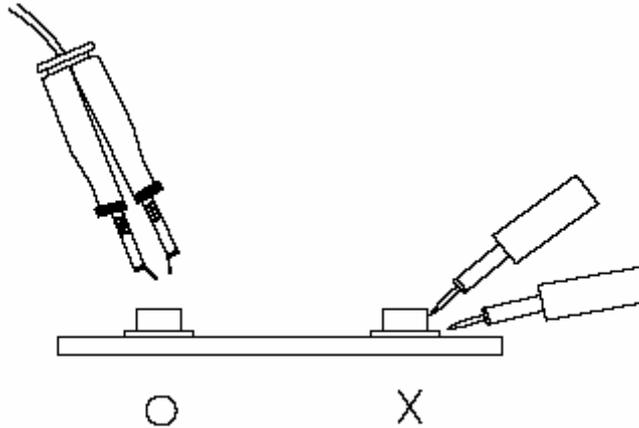
3.4 After soldering, do not warp the circuit board.

4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 260°C for 5 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



6. Caution in ESD

Static Electricity and surge damages the LED. It is recommended to use a wrist band or anti-electrostatic glove when handling the LED. All devices, equipment and machinery must be properly grounded.